



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D

*\* : Required Field*

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2017-11-13
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Authorized Representative *</b>	Rossana Bonaccorso	<b>Representative Title</b>	ADG MD Champion
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

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Legal Statement			
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard

**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	A5Z7*UH01BB6	A	0959	2017-11-13
Amount	UoM	Unit type	ST ECOPACK Grade	
532.29	mg	Each	ECOPACK1	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
3	250	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NA	NiPdAu	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
QFN	3.9-4.9-1.25	20	GULL WING	
Comment	Package: SO 20 .30 TO JEDEC MS-013. MDF valid for CPs: L4979MD013TR and L4979MD			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

Query : California Prop65 list, dated 27th January 2017			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.03	Leadframe	60
Antimony trioxide	4.27	Mold compound	8022

QueryList : REACH-12th January 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	ASZ7*UH01BB6					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	3.099	mg	supplier	die	Silicon (Si)	7440-21-3		2.986	mg	963537	5610
				supplier	metallization	Aluminium (Al)	7429-90-5		0.022	mg	7099	41
				supplier	metallization	Titanium (Ti)	7440-32-6		0.003	mg	968	6
				supplier	Passivation	Silicon Nitride	12033-89-5		0.005	mg	1613	9
				supplier	Passivation	Silicon Oxide	7631-86-9		0.060	mg	19361	113
				supplier	polymer die coating	PIK1 Gamma-butyrolactone	96-48-0		0.023	mg	7422	43
Leadframe	Copper & its alloys	172.179	mg	supplier	alloy	Copper (Cu)	7440-50-8		171.920	mg	998496	322982
				supplier	alloy	Iron (Fe)	7439-89-6		0.079	mg	459	148
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.145	mg	842	272
				supplier	metallization	Nickel (Ni)	7440-02-0		0.032	mg	186	60
				supplier	metallization	Palladium (Pd)	7440-05-3		0.002	mg	11	4
				supplier	metallization	Gold (Au)	7440-57-5		0.001	mg	6	2
Die attach	Other Organic Materials	0.731	mg	supplier	glue	Silver (Ag)	7440-22-4		0.563	mg	770178	1058
				supplier	glue	Epoxy Cresol Novolak	29690-82-2		0.165	mg	225718	310
				supplier	glue	1-isopropyl-2,2-dimethyltrimethylene diisobut	6846-50-0		0.003	mg	4104	6
Bonding wires	Other inorganic materials	0.220	mg	supplier	wire	Gold (Au)	7440-57-5		0.220	mg	1000000	413
Encapsulation	Other Organic Materials	356.061	mg	supplier	mold compound	Silica, vitreous	60676-86-0		286.986	mg	806002	539153
				supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		24.924	mg	69999	46824
				supplier	mold compound	Phenol resin	9003-35-4		14.242	mg	39999	26756
				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		21.364	mg	60001	40136
				supplier	mold compound	Antimony Trioxide	1309-64-4		4.273	mg	12001	8028
				supplier	mold compound	Brominated Epoxy Resin	40039-93-8		2.492	mg	6999	4682
				supplier	mold compound	Carbon black	1333-86-4		1.780	mg	4999	3344